●LGA-8B01 Power Dissipation

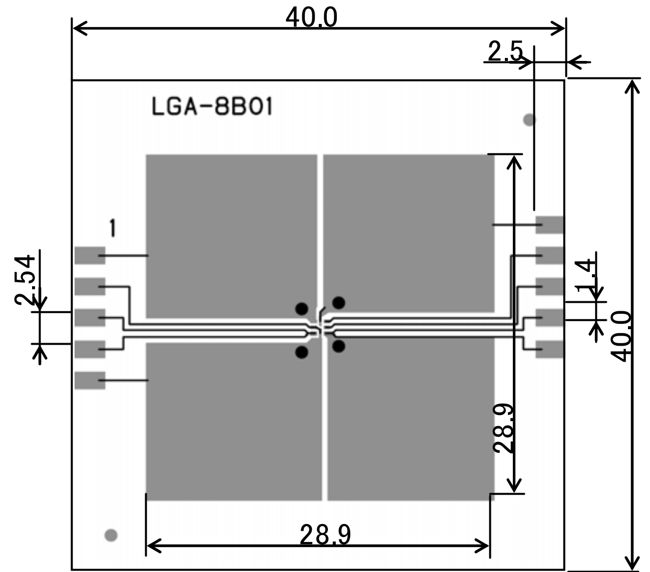
Power dissipation data for the LGA-8B01 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition

Condition:	Mount on a board
Ambient:	Natural convection
Soldering:	Lead (Pb) free
Board:	Dimensions 40mm×40mm (1600mm^2 in one side)
	1st Layer: Approx. 50% connect to lead 1/4/5/8
	2nd Layer: Approx. 50% connect to lead 1/4/5/8
	3rd Layer: Approx. 50% connect to lead 1/4/5/8
	4th Layer: Approx. 50% connect to lead 1/4/5/8
	The copper area is divided into four block,
	one block is 12.5% of total.
	Each terminal connects one copper block in the
	front and one in the back.
Material:	Glass Epoxy (FR-4)
Thickness:	1.6mm
Through-hole:	4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature (105℃)

Board Mount (Tjmax=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	1000	100.00
105	200